

# **TDA18252HN**

## **Cable Silicon Tuner**

Rev. 3 — 16 August 2010

**Product data sheet** 

## 1. General description

The TDA18252HN is a single-chip direct conversion Silicon Tuner IC designed for digital-only cable applications.

The TDA18252HN integrates a loop-through feature that enables the RF input signal to be used as an output for another downconverter. This feature simplifies the application and reduces the Bill Of Materials (BOM).

- The TDA18252HN ensures a low system cost as:
  - Costly components such as low-noise amplifiers, Surface Acoustic Wave (SAW) filters and incremental crystal oscillators are eliminated from the system BOM
- The TDA18252HN high-performance Silicon Tuner meets today's digital cable TV reception needs with:
  - Low power consumption
  - High linearity
  - Low noise figure
- The TDA18252HN ensures ease of use with:
  - Easy on-board integration
  - Efficient and effective PCB design
  - Reduced external components

#### 2. Features and benefits

- Single 3.3 V power supply
- Low power consumption
- Extended frequency coverage of up to 1002 MHz
- Digital cable reception for STB
- RF loop-through
- Fully integrated IF selectivity; eliminating the need for external SAW filters
- Alignment free
- Fully integrated oscillator with no external components
- Integrated wideband gain control
- Crystal oscillator output buffer (16 MHz) for single crystal applications
- I<sup>2</sup>C-bus provides:
  - 3.3 V and 5 V microcontroller compatibility
  - Received Signal Strength Indicator (RSSI) data access
  - Die temperature sensor data access



- ◆ Addressing of up to four tuners in a system
- Lead-free manufacturing

### 3. Quick reference data

Table 1. Quick reference data

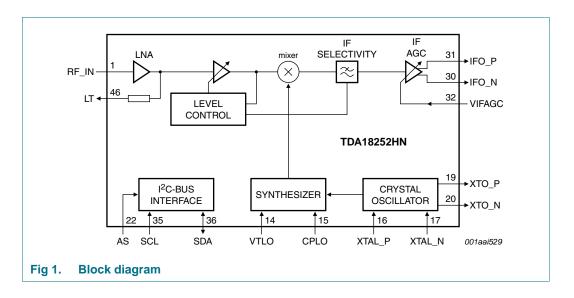
| Symbol                  | Parameter          | Conditions                           | Min | Тур  | Max  | Unit   |
|-------------------------|--------------------|--------------------------------------|-----|------|------|--------|
| $f_{RF}$                | RF frequency       | center of channel                    | 54  | -    | 1002 | MHz    |
| $NF_{tun}$              | tuner noise figure | maximum gain; normal mode            | -   | 7    | 8.5  | dB     |
| φη                      | phase noise        | worst-case in the RF frequency range |     |      |      |        |
|                         |                    | 10 kHz                               | -   | -85  | -    | dBc/Hz |
|                         |                    | 100 kHz                              | -   | -105 | -    | dBc/Hz |
| Р                       | power dissipation  | normal mode                          | -   | 750  | -    | mW     |
| $\alpha_{\text{image}}$ | image rejection    | normal mode                          | 55  | 62   | -    | dB     |

# 4. Ordering information

Table 2. Ordering information

| Type number   | Package |  |          |  |
|---------------|---------|--|----------|--|
|               | Name    | Description  | Version  |  |
| TDA18252HN/C1 | HVQFN48 | plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body $7 \times 7 \times 0.85$ mm | SOT619-1 |  |

## 5. Block diagram



# 6. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter                          | Conditions                            | Min  | Max            | Unit |
|------------------|------------------------------------|---------------------------------------|------|----------------|------|
| $V_{CC}$         | supply voltage                     |                                       | -0.3 | +3.60          | V    |
| $V_{I}$          | input voltage                      | pins SDA and SCL                      | -0.3 | +5.5           | V    |
|                  |                                    | all other pins                        |      |                |      |
|                  |                                    | V <sub>CC</sub> < 3.3 V               | -0.3 | $V_{CC} + 0.3$ | V    |
|                  |                                    | $V_{CC} > 3.3 \text{ V}$              | -0.3 | +3.6           | V    |
| T <sub>stg</sub> | storage temperature                |                                       | -40  | +150           | °C   |
| Tj               | junction temperature               |                                       | -    | 95             | °C   |
| V <sub>ESD</sub> | electrostatic discharge<br>voltage | EIA/JESD22-A114<br>(human body model) | 2    | -              | kV   |
|                  |                                    | EIA/JESD22-A115 (machine model)       | 200  | -              | V    |

### 7. Abbreviations

Table 4. Abbreviations

| Table 11 / Abbreviations |                        |  |  |
|--------------------------|------------------------|--|--|
| Acronym                  | Description            |  |  |
| AGC                      | Automatic Gain Control |  |  |
| IC                       | Integrated Circuit     |  |  |
| ID                       | Identity               |  |  |
| IF                       | Intermediate Frequency |  |  |
| LNA                      | Low-Noise Amplifier    |  |  |
| PCB                      | Printed-Circuit Board  |  |  |
| RF                       | Radio Frequency        |  |  |
| SAW                      | Surface Acoustic Wave  |  |  |
| STB                      | Set-Top Box            |  |  |

# 8. Revision history

Table 5. Revision history

| Document ID           | Release date | Data sheet status  | Change notice | Supersedes |
|-----------------------|--------------|--------------------|---------------|------------|
| TDA18252HN_SDS v.3[1] | 20100816     | Product data sheet | -             | -          |

<sup>[1]</sup> Revisions 1 and 2 are not available.

## **Legal information**

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| Document status[1][2]          | Product status[3] | Definition  |
|--------------------------------|-------------------|---|
| Objective [short] data sheet   | Development       | This document contains data from the objective specification for product development. |
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TDA18252HN SDS

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#### **Cable Silicon Tuner**

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